ABSTRACT

FIG. 3D shows a heat-dissipating device (100) for cooling of heat generated by an electrical or electronic device, example of a laptop (302), during operation. A numbers of heat sinks (106) are positioned in close contact with a hotspot regions (320) of the laptop (302). The heat sinks (106) are coupled to a heat-conductive plate (110) so that heat is transferred away from the laptop (302). The free passage of air flowing across the heat sinks (106) and the heat-conductive plate (110) provide cooling for the laptop (302).

FIG. 3D